

**PATENT APPLICATION**  
**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Docket No: Q78432

Hien Boon TAN, et al.

Appln. No.: 10/721,382

Group Art Unit: 2822

Confirmation No.: 6007

Examiner: David E. Graybill

Filed: November 26, 2003

For: HIGH PERFORMANCE CHIP SCALE LEADFRAME PACKAGE METHOD OF  
MANUFACTURING

**RESPONSE TO NOTICE OF NON-COMPLIANT AMENDMENT**

**MAIL STOP AMENDMENT**

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

In response to the "Notice of Non-Compliant Amendment," mailed December 27, 2007,  
submitted herewith is a corrected AMENDMENT TO THE CLAIMS section.

**TABLE OF CONTENTS**

AMENDMENTS TO THE CLAIMS .....	2
REMARKS .....	